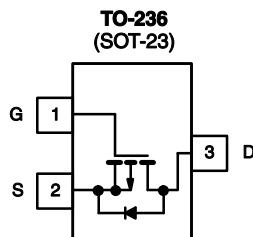


P-Channel 1.25-W, 1.8-V (G-S) MOSFET

PRODUCT SUMMARY		
V _{DS} (V)	r _{DS(on)} (Ω)	I _D (A)
- 20	0.065 at V _{GS} = - 4.5 V	± 3.2
	0.085 at V _{GS} = - 2.5 V	± 2.0

FEATURES

Power MOSFETs: 1.8 V Rated



Top View

Si2305

*Marking Code

ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted				
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	- 20	V	
Gate-Source Voltage	V _{GS}	± 12		
Continuous Drain Current (T _J = 150 °C)	I _D	± 3.2	A	
T _A = 70 °C		± 2.0		
Pulsed Drain Current	I _{DM}	± 12		
Continuous Source Current (Diode Conduction) ^{a, b}	I _S	- 1.6		
Maximum Power Dissipation ^{a, b}	P _D	1.25	W	
T _A = 70 °C		0.8		
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS				
Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^a	R _{thJA}	t ≤ 5 sec	100	°C/W
Steady State		130		

Notes:

a. Surface Mounted on FR4 Board.

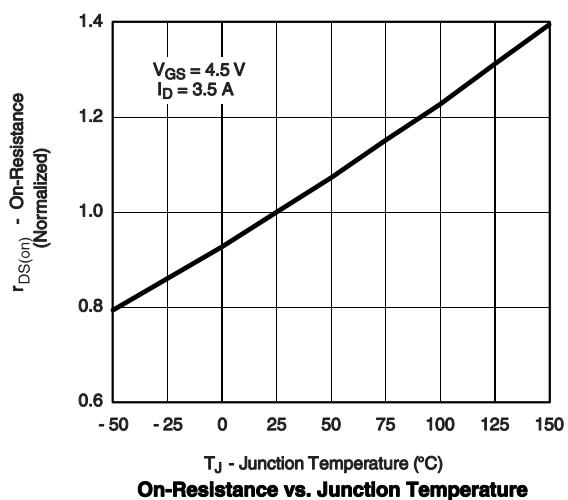
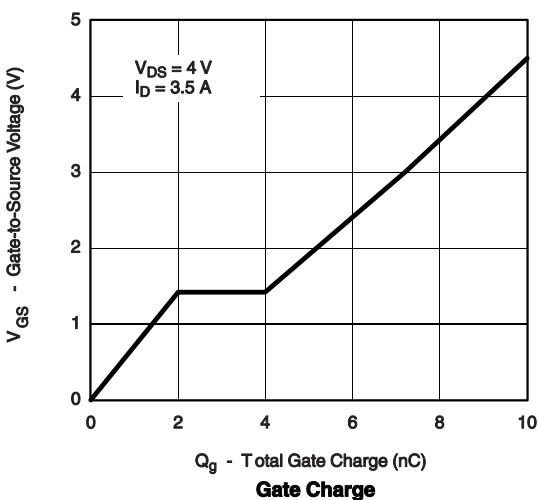
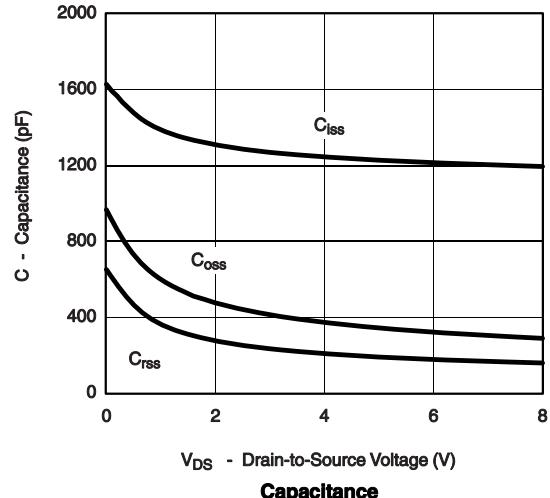
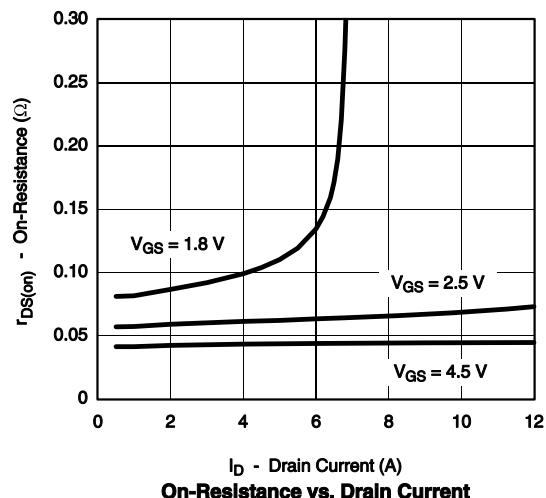
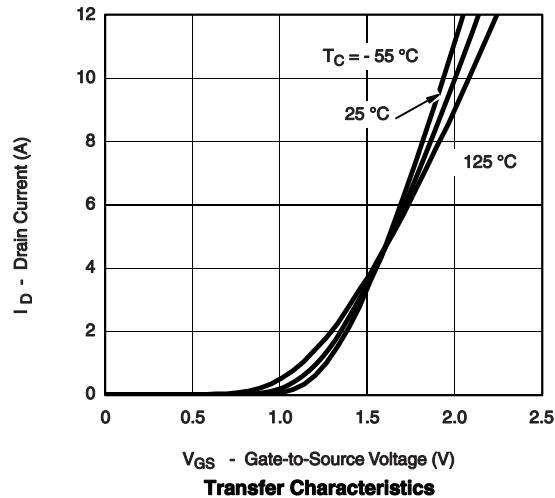
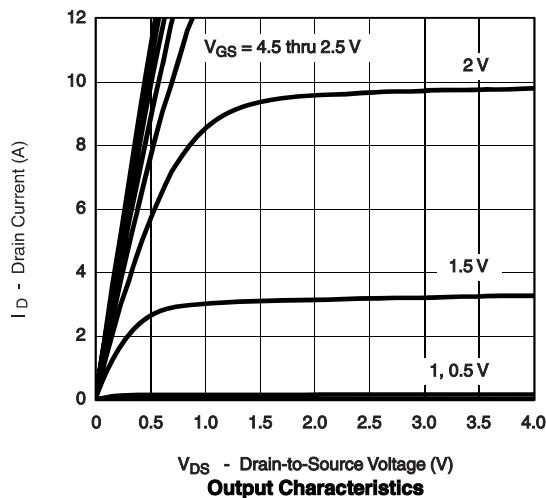
b. t ≤ 5 sec.

SPECIFICATIONS $T_J = 25^\circ\text{C}$, unless otherwise noted						
Parameter	Symbol	Test Conditions	Limits			Unit
			Min	Typ	Max	
Static						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0 \text{ V}, I_D = -10 \mu\text{A}$	-20			V
Gate-Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = -250 \mu\text{A}$	-0.45		-1	
Gate-Body Leakage	I_{GSS}	$V_{\text{DS}} = 0 \text{ V}, V_{\text{GS}} = \pm 12 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = -16 \text{ V}, V_{\text{GS}} = 0 \text{ V}$			-50	nA
On-State Drain Current ^a	$I_{\text{D}(\text{on})}$	$V_{\text{DS}} \leq -5 \text{ V}, V_{\text{GS}} = -4.5 \text{ V}$	-6			A
		$V_{\text{DS}} \leq -5 \text{ V}, V_{\text{GS}} = -2.5 \text{ V}$	-3			
Drain-Source On-Resistance ^a	$r_{\text{DS}(\text{on})}$	$V_{\text{GS}} = -4.5 \text{ V}, I_D = -3.2 \text{ A}$			0.065	Ω
		$V_{\text{GS}} = -2.5 \text{ V}, I_D = -2 \text{ A}$			0.085	
Forward Transconductance ^a	g_{fs}	$V_{\text{DS}} = -5 \text{ V}, I_D = -3.2 \text{ A}$		8.5		S
Diode Forward Voltage	V_{SD}	$I_S = -1.6 \text{ A}, V_{\text{GS}} = 0 \text{ V}$			-1.28	V
Dynamic^b						
Total Gate Charge	Q_g	$V_{\text{DS}} = -4 \text{ V}, V_{\text{GS}} = -4.5 \text{ V}, I_D \geq -3.5 \text{ A}$		10	15	nC
Gate-Source Charge	Q_{gs}			2		
Gate-Drain Charge	Q_{gd}			2		
Input Capacitance	C_{iss}	$V_{\text{DS}} = -4 \text{ V}, V_{\text{GS}} = 0 \text{ V}, f = 1 \text{ MHz}$		1245		pF
Output Capacitance	C_{oss}			375		
Reverse Transfer Capacitance	C_{rss}			210		
Switching^b						
Turn-On Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = -4 \text{ V}, R_L = 4 \Omega$ $I_D \geq -1.0 \text{ A}, V_{\text{GEN}} = -4.5 \text{ V}, R_G = 6 \Omega$		13	20	ns
	t_r			25	40	
Turn-Off Time	$t_{\text{d}(\text{off})}$			55	80	
	t_f			19	35	

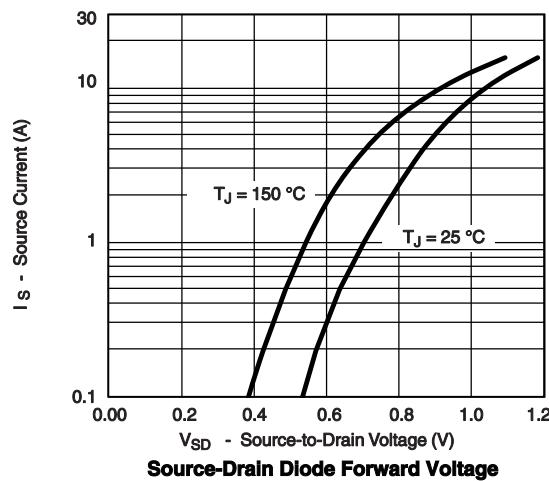
Notes:

- a. For DESIGN AID ONLY, not subject to production testing.
- b. Pulse test: PW $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.
- c. Switching time is essentially independent of operating temperature.

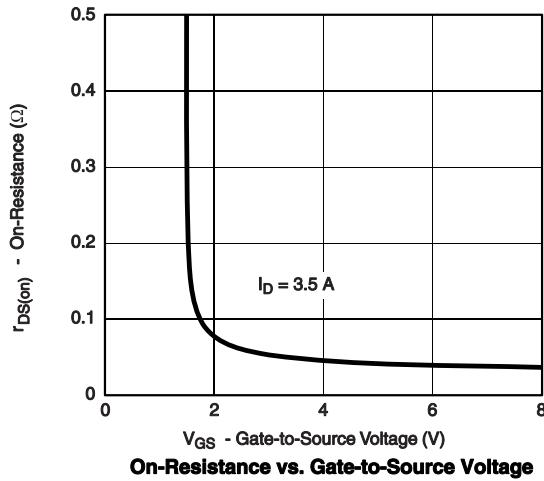
TYPICAL CHARACTERISTICS 25 °C, unless noted



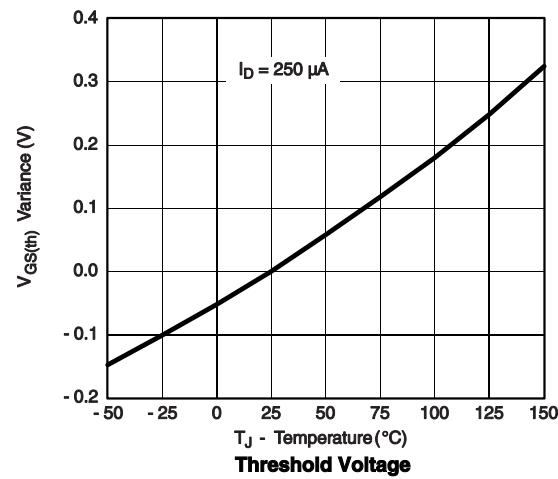
TYPICAL CHARACTERISTICS 25 °C, unless noted



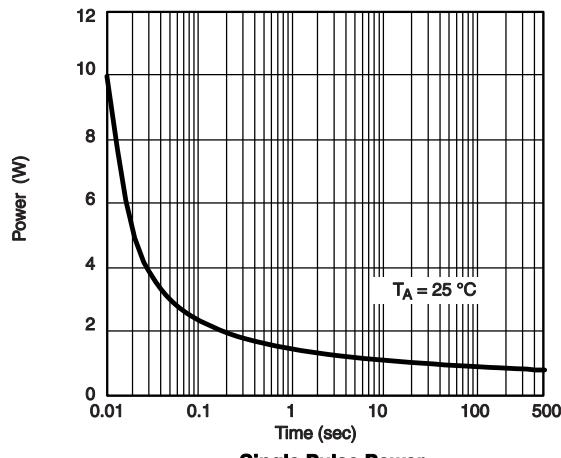
Source-Drain Diode Forward Voltage



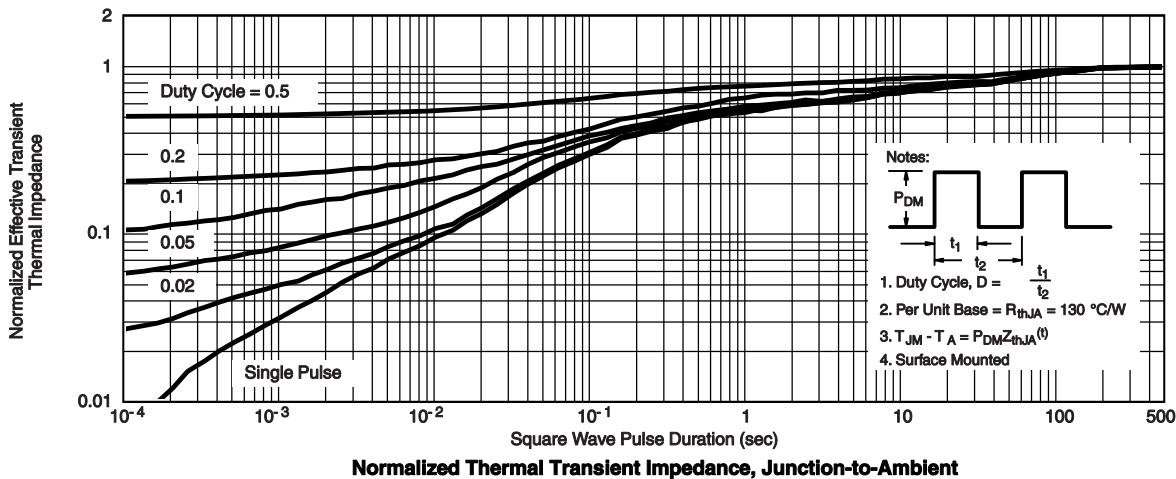
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Single Pulse Power



Normalized Thermal Transient Impedance, Junction-to-Ambient